

10/005667

**METHOD OF FABRICATING AN INTEGRATED CIRCUIT THAT  
SEALS A MEMS DEVICE WITHIN A CAVITY**

5

**ABSTRACT OF THE DISCLOSURE**

10 A method of fabricating an integrated circuit that includes a microelectromechanical (MEMS) device. The method includes forming a MEMS device on a substrate and forming an integrated circuit. The method further includes coupling the substrate to the integrated circuit to form a sealed cavity that includes the MEMS device. The substrate and the integrated circuit are coupled together in a controlled environment to establish a controlled environment within the cavity where the MEMS device is located.

"Express Mail" mailing label number: EL873859534US

Date of Deposit: November 2, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.